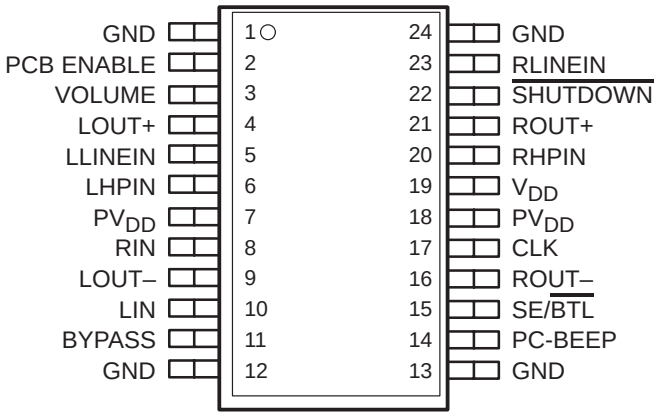
- **Compatible With PC 99 Desktop Line-Out Into 10-kΩ Load**
- **Compatible With PC 99 Portable Into 8-Ω Load**
- **Internal Gain Control, Which Eliminates External Gain-Setting Resistors**
- **DC Volume Control From 20 dB to –40 dB**
- **2-W/Ch Output Power Into 3-Ω Load**
- **PC-Beep Input**
- **Depop Circuitry**
- **Stereo Input MUX**
- **Fully Differential Input**
- **Low Supply Current and Shutdown Current**
- **Surface-Mount Power Packaging 24-Pin TSSOP PowerPAD™**

PWP PACKAGE
(TOP VIEW)



description

The TPA0142 is a stereo audio power amplifier in a 24-pin TSSOP thermally enhanced package capable of delivering 2 W of continuous RMS power per channel into 3-Ω loads. This device minimizes the number of external components needed, which simplifies the design and frees up board space for other features. When driving 1 W into 8-Ω speakers, the TPA0142 has less than 0.22% THD+N across its specified frequency range.

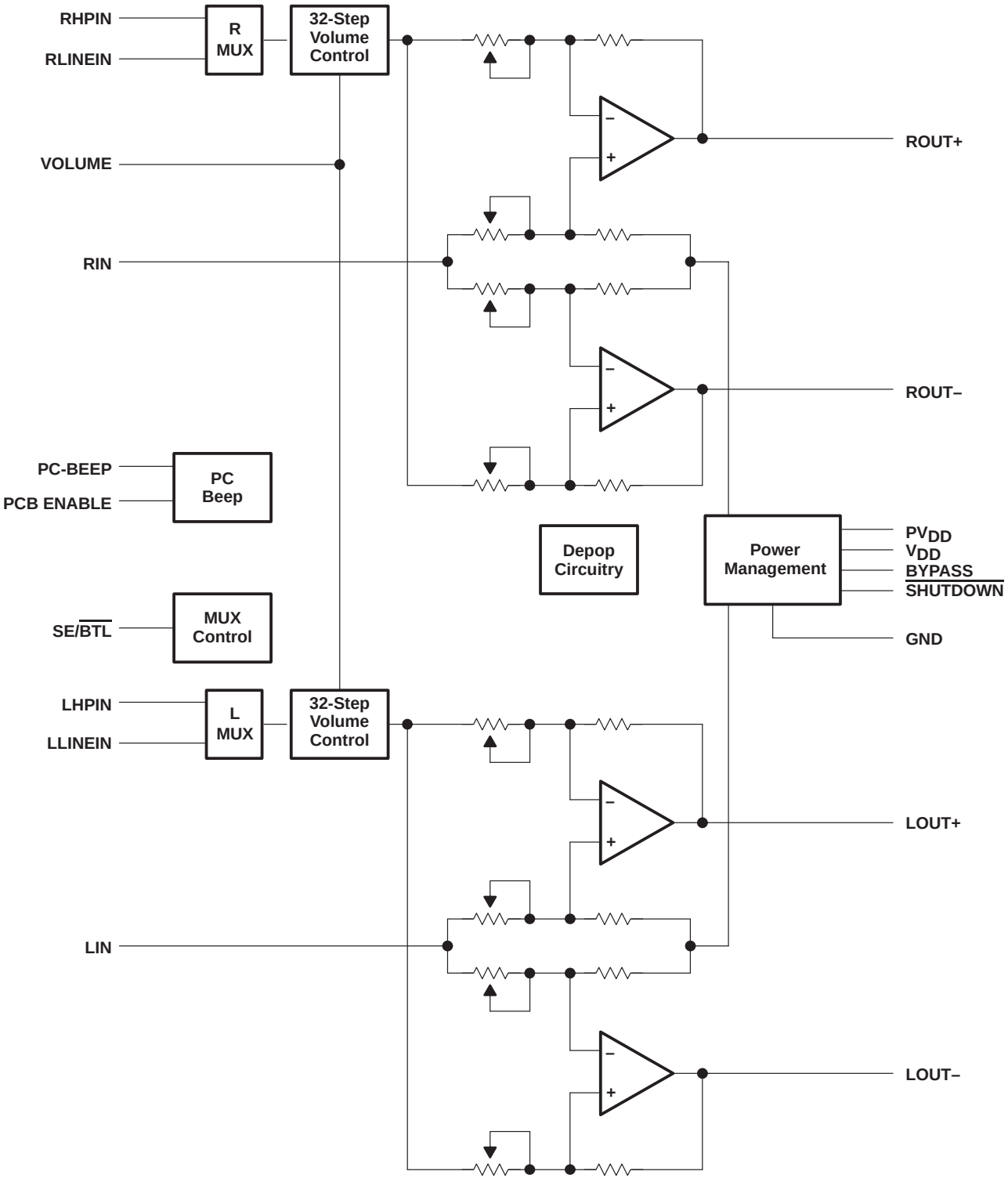
Included within this device is integrated depop circuitry that virtually eliminates transients that cause noise in the speakers.

Amplifier gain is controlled by a dc voltage input on the VOLUME terminal. There are 31 discrete steps covering the range of 20 dB (maximum volume setting) to –40 dB (minimum volume setting) in 2 dB steps. When the VOLUME terminal exceeds 3.54 V, the device is muted. An internal input MUX allows two sets of stereo inputs to the amplifier. In notebook applications, where internal speakers are driven as BTL and the line outputs (often headphone drive) are required to be SE, the TPA0142 automatically switches into SE mode when the SE/$\overline{\text{BTL}}$ input is activated, and this effectively reduces the gain by 6 dB.

The TPA0142 consumes only 20 mA of supply current during normal operation. A miserly shutdown mode reduces the supply current to less than 150 μA.

The PowerPAD package (PWP) delivers a level of thermal performance that was previously achievable only in TO-220-type packages. Thermal impedances of approximately 35°C/W are truly realized in multilayer PCB applications. This allows the TPA0142 to operate at full power into 8-Ω loads at ambient temperatures of 85°C.

functional block diagram



AVAILABLE OPTIONS

T_A	PACKAGED DEVICE
	TSSOP† (PWP)
–40°C to 85°C	TPA0142PWP

† The PWP package is available taped and reeled. To order a taped and reeled part, add the suffix R to the part number (e.g., TPA0142PWPR).

Terminal Functions

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
BYPASS	11		Tap to voltage divider for internal mid-supply bias generator
CLK	17	I	If a 47-nF capacitor is attached, the TPA0142 generates an internal clock. An external clock can override the internal clock input to this terminal.
GND	1, 12 13, 24		Ground connection for circuitry. Connected to thermal pad
LHPIN	6	I	Left channel headphone input, selected when SE/$\overline{\text{BTL}}$ is held high
LIN	10	I	Common left input for fully differential input. AC ground for single-ended inputs
LLINEIN	5	I	Left channel line negative input, selected when SE/$\overline{\text{BTL}}$ is held low
LOUT+	4	O	Left channel positive output in $\overline{\text{BTL}}$ mode and positive output in SE mode
LOUT–	9	O	Left channel negative output in $\overline{\text{BTL}}$ mode and high-impedance in SE mode
PCB ENABLE	2	I	If this terminal is high, the detection circuitry for PC-BEEP is overridden and passes PC-BEEP through the amplifier, regardless of its amplitude. If PCB ENABLE is floating or low, the amplifier continues to operate normally.
PC-BEEP	14	I	The input for PC Beep mode. PC-BEEP is enabled when a > 1-V (peak-to-peak) square wave is input to PC-BEEP or PCB ENABLE is high.
PV_{DD}	7, 18	I	Power supply for output stage
RHPIN	20	I	Right channel headphone input, selected when SE/$\overline{\text{BTL}}$ is held high
RIN	8	I	Common right input for fully differential input. AC ground for single-ended inputs
RLINEIN	23	I	Right channel line input, selected when SE/$\overline{\text{BTL}}$ is held low
ROUT+	21	O	Right channel positive output in $\overline{\text{BTL}}$ mode and positive output in SE mode
ROUT–	16	O	Right channel negative output in $\overline{\text{BTL}}$ mode and high-impedance in SE mode
SE/$\overline{\text{BTL}}$	15	I	Input MUX control input. When this terminal is held high, the LHPIN or RHPIN and SE output is selected. When this terminal is held low, the LLINEIN or RLINEIN and BTL output are selected.
$\overline{\text{SHUTDOWN}}$	22	I	When held low, this terminal places the entire device, except PC-BEEP detect circuitry, in shutdown mode.
V_{DD}	19	I	Analog V_{DD} input supply. This terminal needs to be isolated from PV_{DD} to achieve highest performance.
VOLUME	3	I	VOLUME detects the dc level at the terminal and sets the gain for 31 discrete steps covering a range of 20 dB to –40 dB for dc levels of 0.15 V to 3.54. When the dc level is over 3.54 V, the device is muted.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{DD} . . . . . 6 V
Input voltage, V_I . . . . . –0.3 V to V_{DD} +0.3 V
Continuous total power dissipation . . . . . internally limited (see Dissipation Rating Table)
Operating free-air temperature range, T_A . . . . . –40°C to 85°C
Operating junction temperature range, T_J . . . . . –40°C to 150°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$	DERATING FACTOR	$T_A = 70°C$	$T_A = 85°C$
PWP	2.7 W‡	21.8 mW/°C	1.7 W	1.4 W

‡ Please see the Texas Instruments document, *PowerPAD Thermally Enhanced Package Application Report* (literature number SLMA002), for more information on the PowerPAD package. The thermal data was measured on a PCB layout based on the information in the section entitled *Texas Instruments Recommended Board for PowerPAD* on page 33 of the before mentioned document.

recommended operating conditions

		MIN	MAX	UNIT
Supply voltage, V_{DD}		4.5	5.5	V
High-level input voltage, V_{IH}	SE/$\overline{\text{BTL}}$	4		V
	$\overline{\text{SHUTDOWN}}$	2		
Low-level input voltage, V_{IL}	SE/$\overline{\text{BTL}}$		3	V
	$\overline{\text{SHUTDOWN}}$		0.8	
Operating free-air temperature, T_A		–40	85	°C

electrical characteristics at specified free-air temperature, V_{DD} = 5 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$\|V_{OD}\|$	Differential output voltage				25	mV
PSRR	Power supply rejection ratio	V_{DD} = 4.9 V to 5.1 V		67		dB
$\|I_{IH}\|$	High-level input current	V_{DD} = 5.5 V, $V_I = V_{DD}$			900	nA
$\|I_{IL}\|$	Low-level input current	V_{DD} = 5.5 V, V_I = 0 V			900	nA
I_{DD}	Supply current	BTL mode		20		mA
		SE mode		10		
$I_{DD(sd)}$	Supply current, shutdown mode			150	300	µA

operating characteristics, V_{DD} = 5 V, T_A = 25°C, R_L = 4 Ω, Gain = 2 V/V, BTL mode (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
P_O	Output power	THD = 1%,	f = 1 kHz		2		W
THD + N	Total harmonic distortion plus noise	P_O = 1 W,	f = 20 Hz to 15 kHz		0.22%		
B_{OM}	Maximum output power bandwidth	THD = 5%			>15		kHz
k_{SVR}	Supply ripple rejection ratio	f = 1 kHz, C_B = 0.47 µF	BTL mode		65		dB
			SE mode		60		
V_n	Noise output voltage	C_B = 0.47 µF, f = 20 Hz to 20 kHz	BTL mode		34		μV_{RMS}
			SE mode		44		

APPLICATION INFORMATION

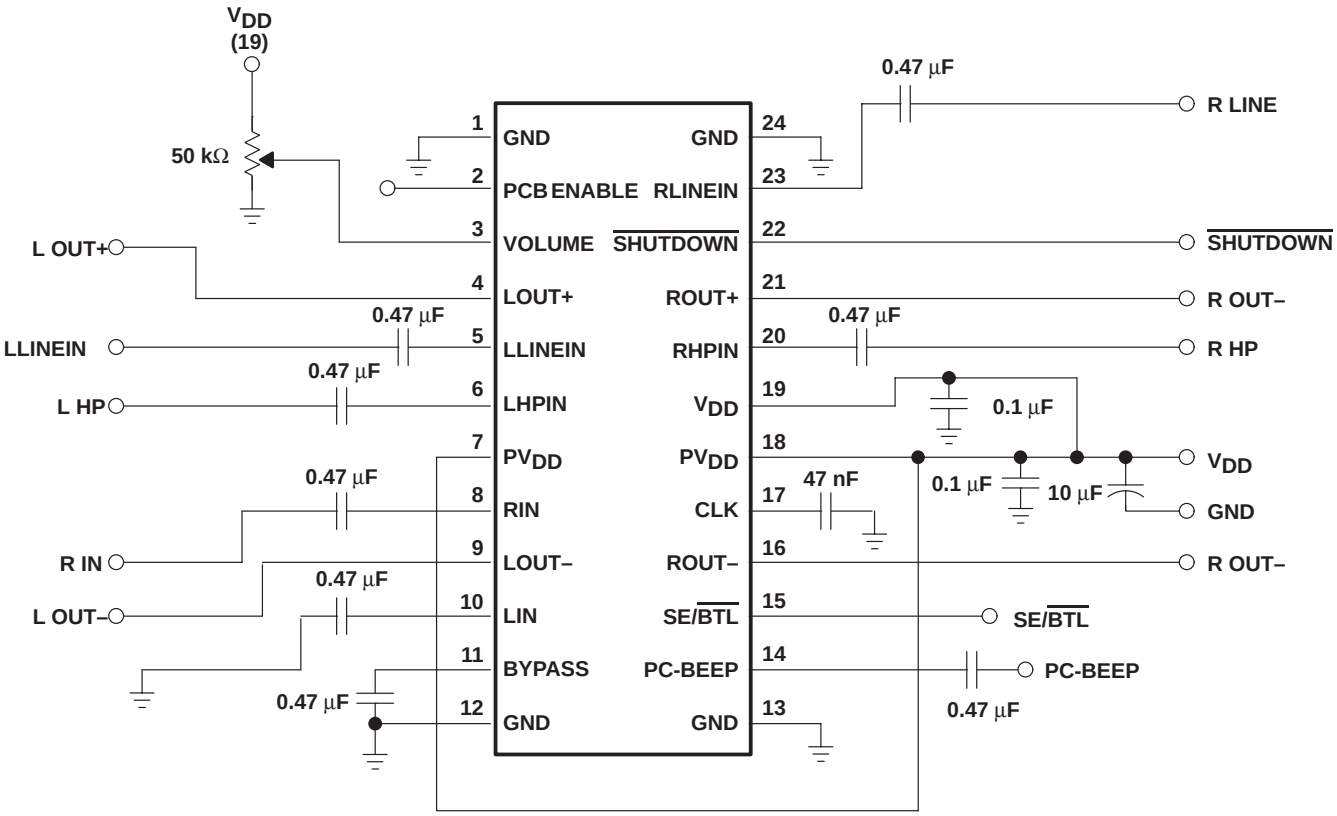


Figure 1. Typical TPA0142 Application Circuit

APPLICATION INFORMATION

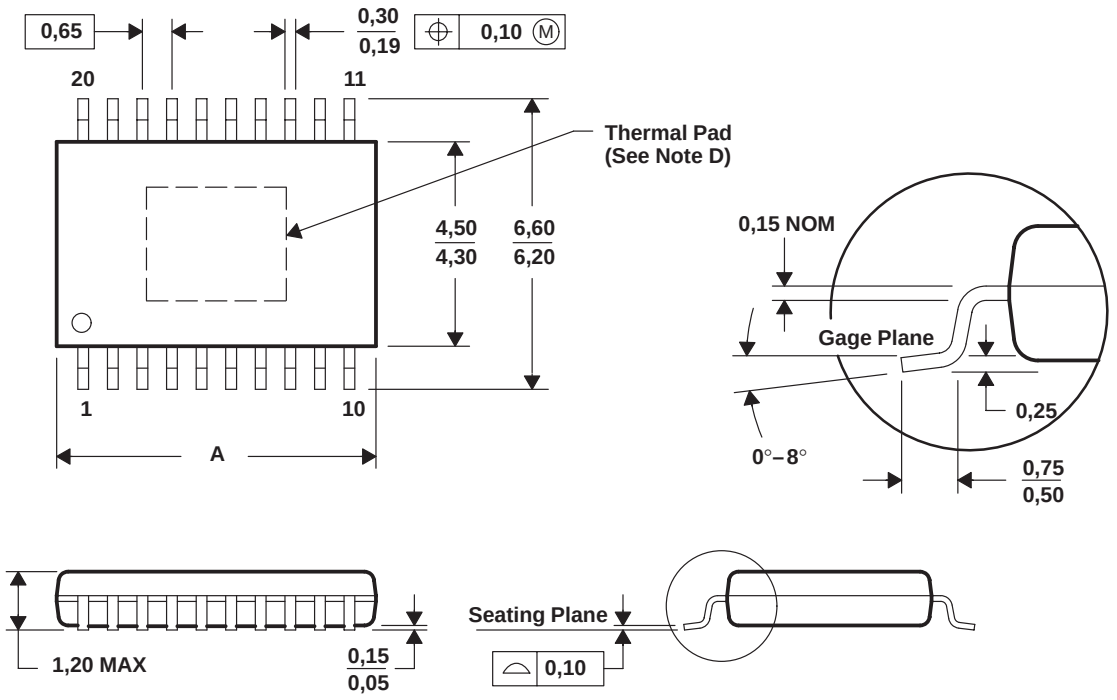
Table 1. DC Volume Control

VOLUME (Terminal 3)		GAIN of AMPLIFIER (dB)
FROM (V)	TO (V)	
0	0.15	20
0.15	0.28	18
0.28	0.39	16
0.39	0.5	14
0.5	0.61	12
0.61	0.73	10
0.73	0.84	8
0.84	0.95	6
0.95	1.06	4
1.06	1.17	2
1.17	1.28	0
1.28	1.39	–2
1.39	1.5	–4
1.5	1.62	–6
1.62	1.73	–8
1.73	1.84	–10
1.84	1.95	–12
1.95	2.07	–14
2.07	2.18	–16
2.18	2.29	–18
2.29	2.41	–20
2.41	2.52	–22
2.52	2.63	–24
2.63	2.74	–26
2.74	2.86	–28
2.86	2.97	–30
2.97	3.08	–32
3.08	3.2	–34
3.2	3.31	–36
3.31	3.42	–38
3.42	3.54	–40
3.54	5	–85

MECHANICAL DATA

PWP (R-PDSO-G)** **PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE**

20-PIN SHOWN



DIM \ PINS **	14	16	20	24	28
A MAX	5,10	5,10	6,60	7,90	9,80
A MIN	4,90	4,90	6,40	7,70	9,60

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NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusions.
D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
E. Falls within JEDEC MO-153

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